



Material Content Data Sheet



Sales Product Name	IDH08S60C			Issued		7. December 2015		
MA#	MA000703444							
Package	PG-TO220-2-1			Weight*		1969.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.143	0.11	0.11	1088	1088
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		382	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
	non noble metal	copper	7440-50-8	751.797	38.19	38.24	381716	382214
wire	non noble metal	aluminium	7429-90-5	1.227	0.06	0.06	623	623
encapsulation	organic material	carbon black	1333-86-4	9.068	0.46		4604	
	plastics	epoxy resin	-	99.753	5.06		50649	
	inorganic material	silicondioxide	60676-86-0	495.743	25.17	30.69	251708	306961
leadfinish	non noble metal	tin	7440-31-5	14.668	0.74	0.74	7447	7447
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	1	101
solder	noble metal	silver	7440-22-4	0.093	0.00		47	
	non noble metal	tin	7440-31-5	0.074	0.00		38	
	non noble metal	lead	7439-92-1	3.537	0.18	0.18	1796	1881
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		300	
	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	copper	7440-50-8	589.466	29.93	29.97	299295	299685
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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